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United States Patent [19]

Nakagome et al.

[11] **Patent Number: Des. 365,584**

[45] **Date of Patent: **Dec. 26, 1995**

[54] **SEMICONDUCTOR MANUFACTURING DEVICE**

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[73] Assignees: **Tokyo Electron Kabushiki Kaisha**, Tokyo; **Tokyo Electron Yamanashi Kabushiki Kaisha**, Nirasaki, both of Japan

[**] Term: **14 Years**

[21] Appl. No.: **24,005**

[22] Filed: **Jun. 6, 1994**

[30] **Foreign Application Priority Data**

Dec. 15, 1993 [JP] Japan 5-37970

[52] **U.S. Cl.** **D15/199**; D10/46; D10/75

[58] **Field of Search** .... D10/46, 75; D15/199; 29/25.01, 33 R, 722, 855; 55/385.2; 156/643, 646, 653, 656; 228/4.5, 175; 257/288, 690, 730, 786; 414/217, 225, 935–941; 437/180–187, 189, 196, 203, 204, 205, 209, 902; 454/182, 851

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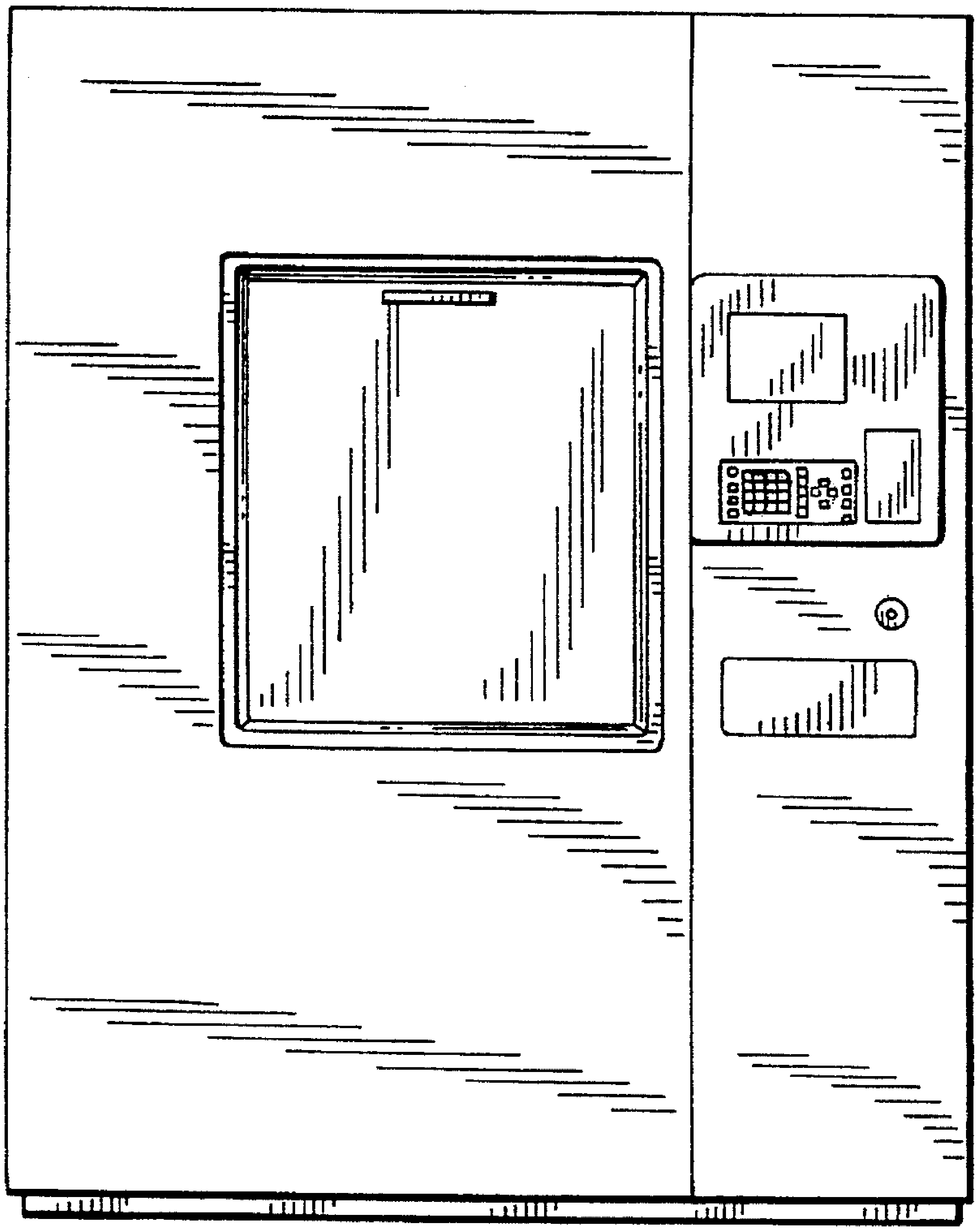
[57] **CLAIM**

The ornamental design for a semiconductor manufacturing device, as shown.

DESCRIPTION

FIG. **1** is a front view of a semiconductor manufacturing device showing my new design;
FIG. **2** is a rear view thereof;
FIG. **3** is a right side view thereof;
FIG. **4** is a left side view thereof;
FIG. **5** is a top view thereof; and,
FIG. **6** is a bottom view thereof.

1 Claim, 4 Drawing Sheets



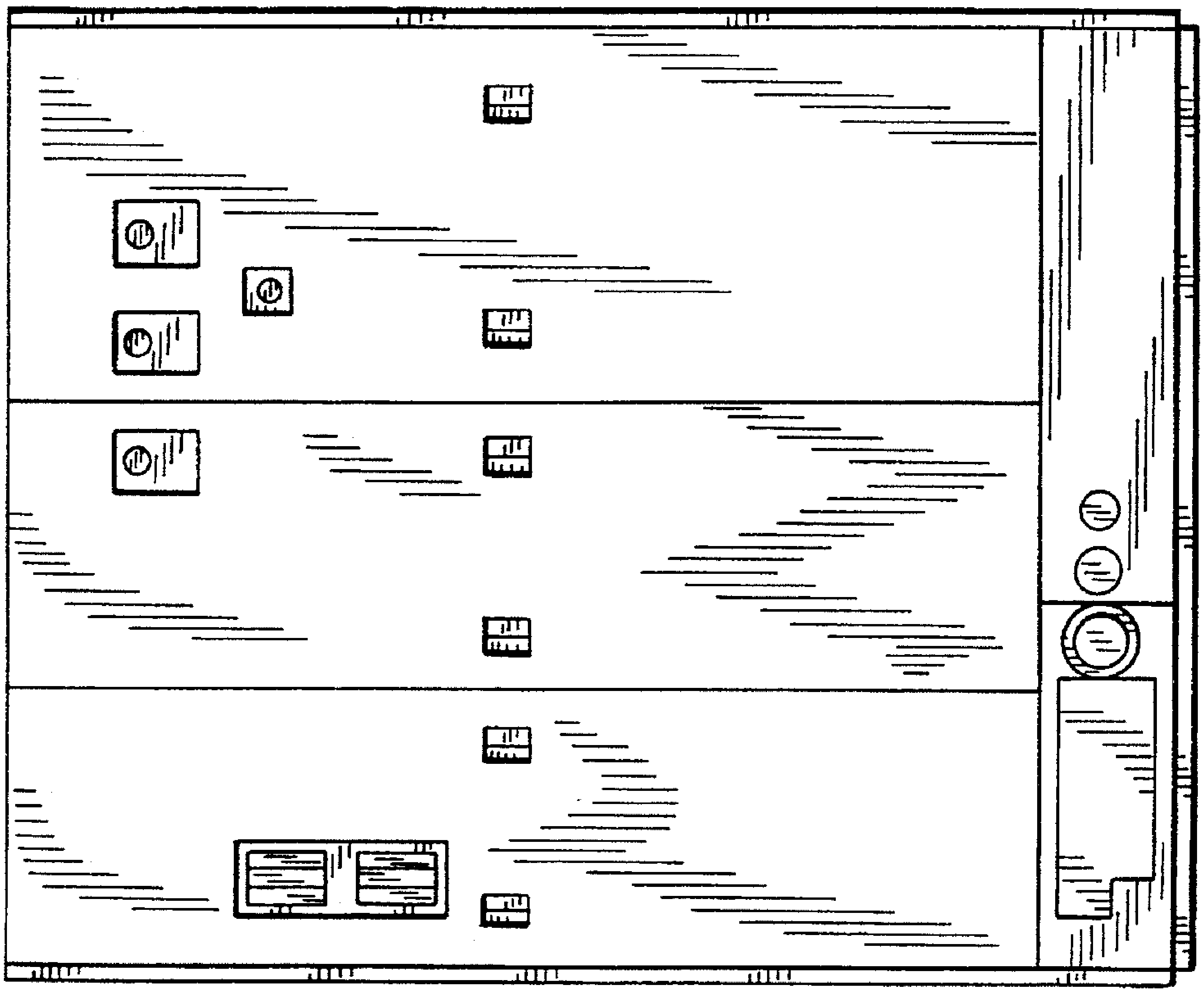


FIG. 2

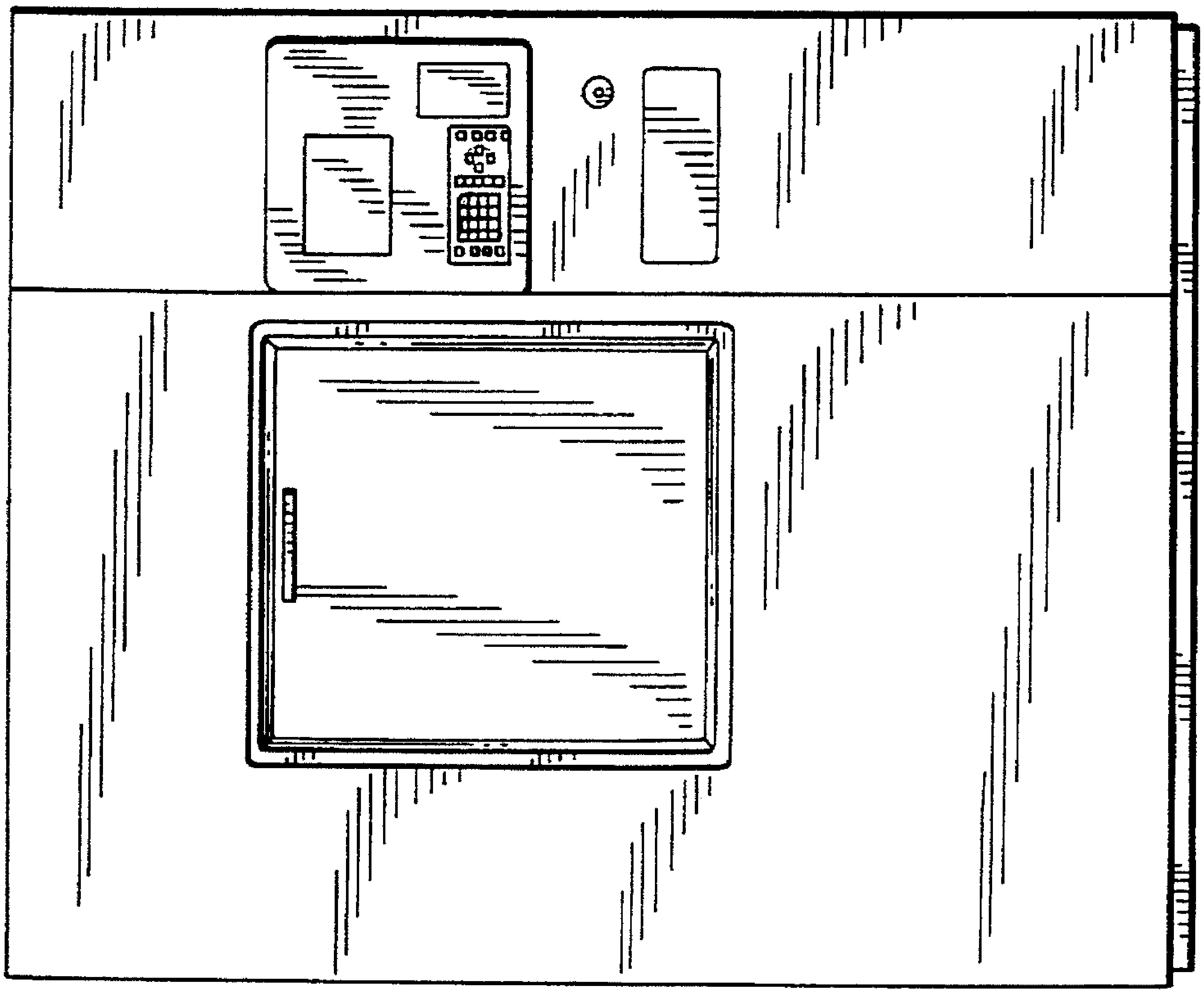


FIG. 1

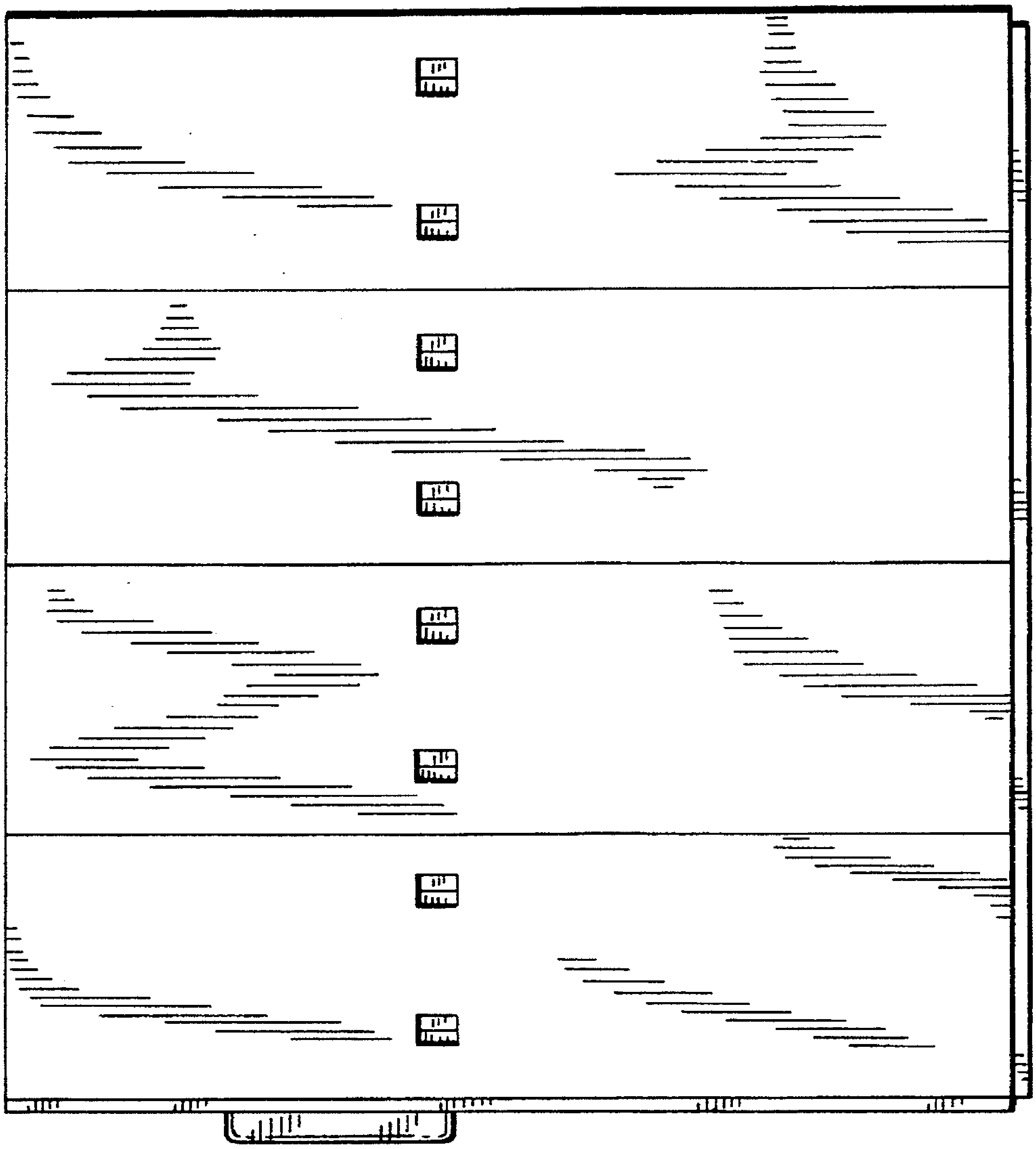


FIG. 3

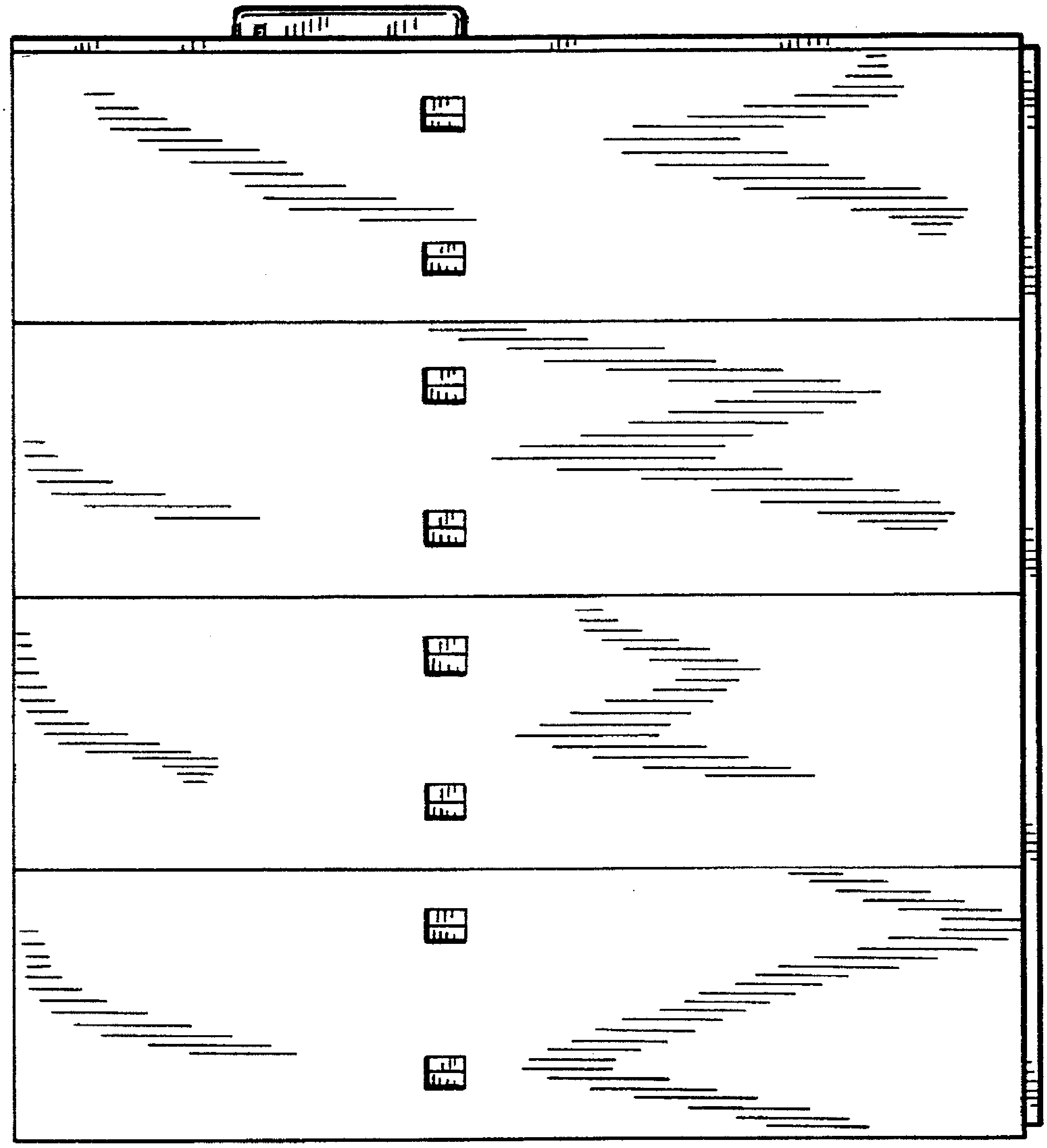


FIG. 4

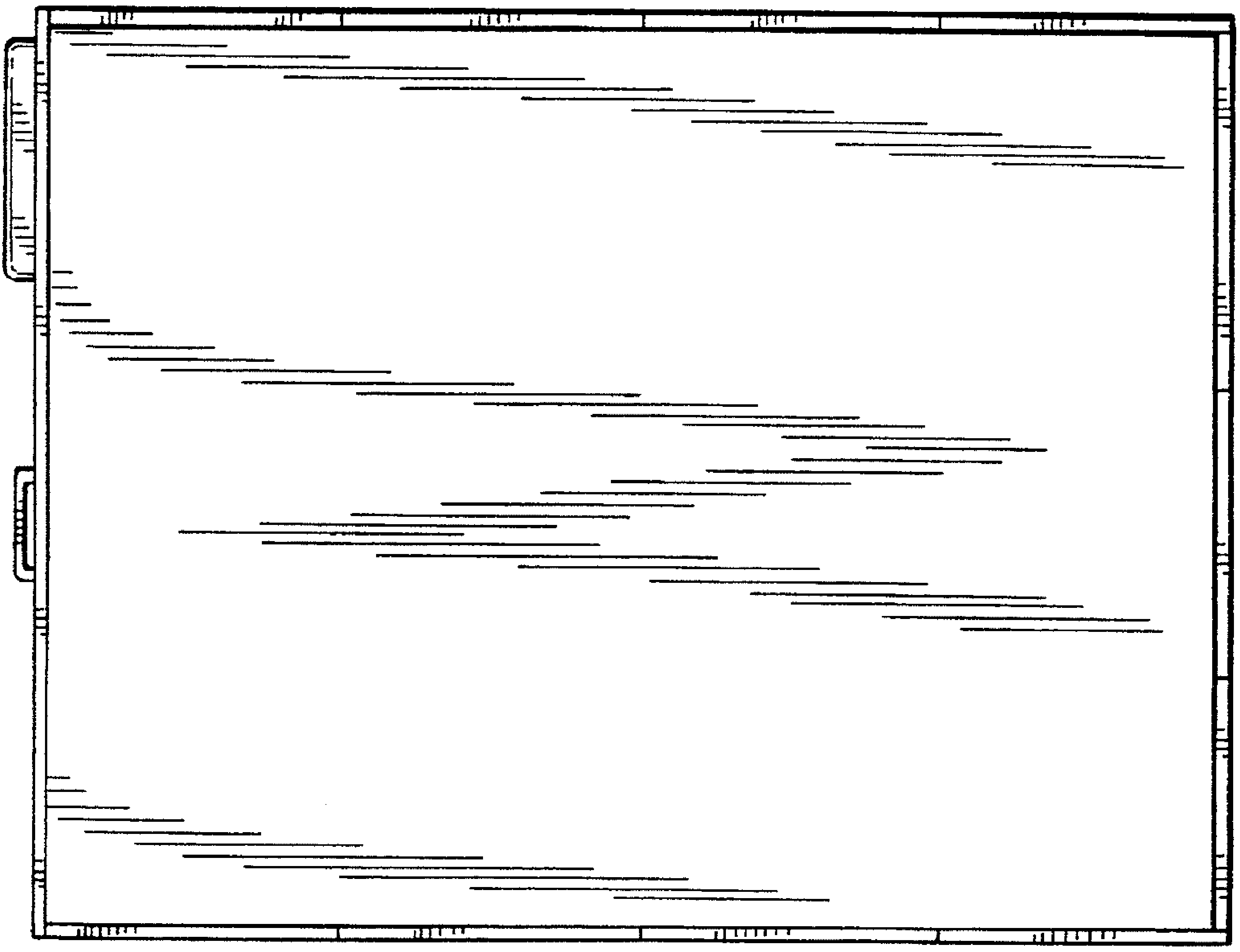


FIG. 6

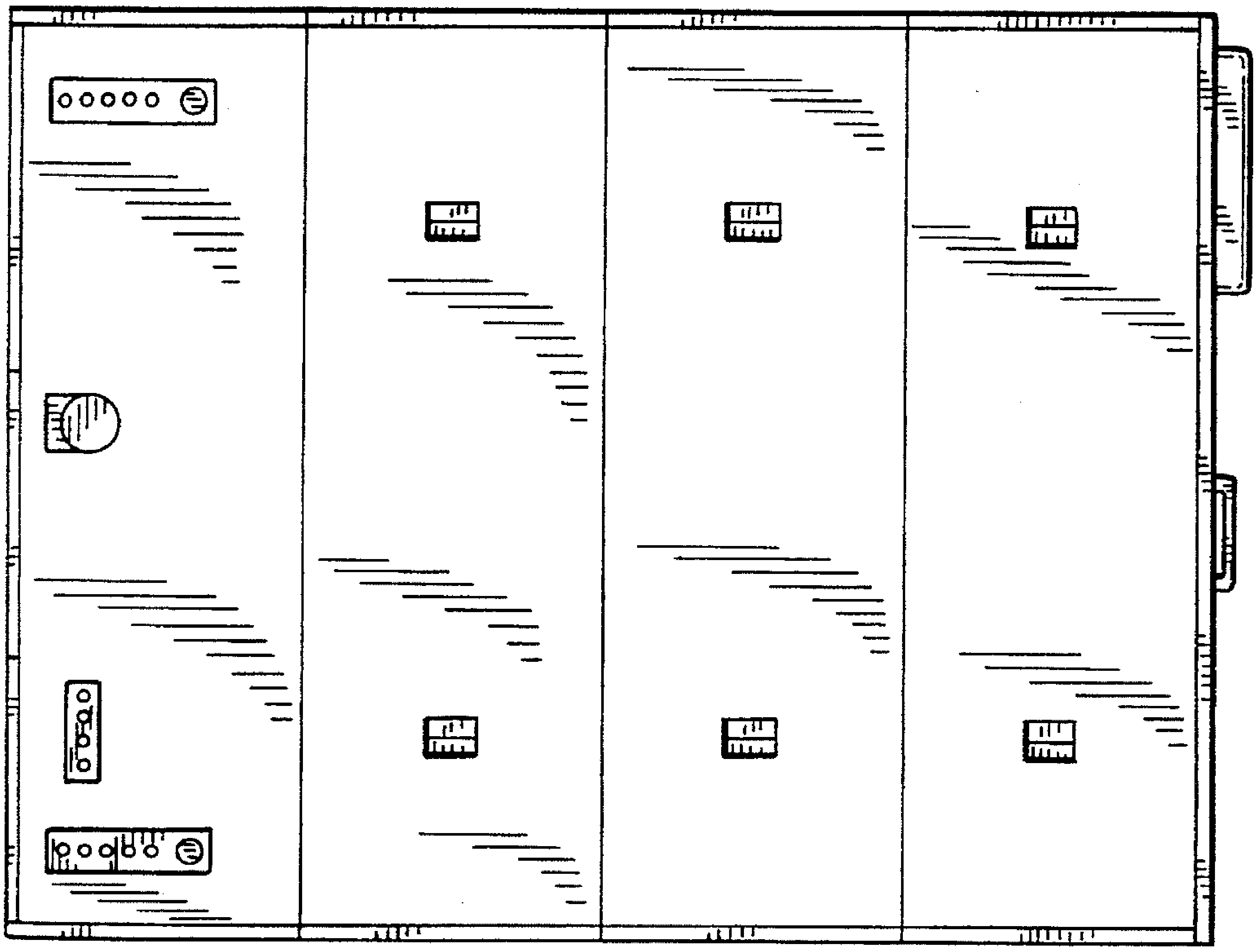


FIG. 5